

CLAIMS

1. High speed high data interconnect apparatus comprising:

a stiffening plate with optical fiber mounting groove defined on a surface thereof;

a length of optical fiber with opposed ends and defining an optical path between the opposed ends, the optical fiber being mounted in the groove on the surface of the stiffening plate in a longitudinally extending direction generally parallel to the surface of the stiffening plate;

a reflecting surface positioned adjacent one of the opposed ends of the optical fiber, the reflecting surface being positioned to direct light at an angle of approximately ninety degrees to the optical path between the opposed ends of the optical fiber; and

a printed circuit board laminate encasing the stiffening plate and the optical fiber and including a light via for the passage of light reflected by the reflecting surface, and bond pads formed on a surface of the printed

circuit board laminate adjacent the light via for the electrical connection of a light element.

2. High speed data interconnect apparatus as claimed in claim 1 wherein the light element includes one of a vertical cavity surface emitting laser and a photo detector mounted on the surface of the printed circuit board laminate in light communication with the light via, using the bond pads formed adjacent the light via.

3. High speed data interconnect apparatus as claimed in claim 1 further including a second reflecting surface positioned adjacent another of the opposed ends, the second reflecting surface being positioned to direct light at an angle of approximately ninety degrees to the optical path between the opposed ends of the optical fiber, a second light via for the passage of light reflected by the second reflecting surface, and bond pads formed on a surface of the printed circuit board laminate adjacent the second light via for the electrical connection of a second light element.

4. High speed data interconnect apparatus as claimed in claim 3 wherein the light element includes a vertical cavity surface emitting laser and the second light element includes a photo detector.

5. High speed data interconnect apparatus as claimed in claim 1 wherein the stiffening plate includes nickel iron.

6. High speed data interconnect apparatus as claimed in claim 1 wherein the printed circuit board laminate encasing the stiffening plate includes Teflon.

7. High speed data interconnect apparatus as claimed in claim 1 wherein the optical fiber mounting groove in the stiffening plate has a generally rectangular shaped cross-section with a depth and width approximately equal to a diameter of the length of optical fiber.

8. High speed data interconnect apparatus as claimed in claim 1 wherein the optical fiber mounting groove in the

stiffening plate has a shallow rectangular shaped cross-section with a depth and width smaller than a diameter of the length of optical fiber.

9. High speed data interconnect apparatus as claimed in claim 1 wherein the optical fiber mounting groove in the stiffening plate has a generally V-shaped cross-section.

10. High speed data interconnect apparatus as claimed in claim 1 wherein the reflecting surface includes a cut in the optical fiber adjacent the one of the opposed ends of the optical fiber defining a cut surface positioned at an angle of approximately 45 degrees to the optical path.

11. High speed data interconnect apparatus as claimed in claim 10 wherein the cut surface has a reflecting material positioned thereon.

12. High speed data interconnect apparatus as claimed in claim 1 wherein the reflecting surface includes a micro mirror mounted in the groove on the surface of the

stiffening plate in optical alignment with the optical path and the light via.

13. High speed data interconnect apparatus as claimed in claim 1 wherein the reflecting surface includes an optical fiber portion with an approximately 45 degree mirrored end mounted in the groove on the surface of the stiffening plate in optical alignment with the optical path and the light via.

14. High speed data interconnect apparatus as claimed in claim 1 including in addition an edge emitting laser mounted in the groove on the surface of the stiffening plate in optical alignment with the optical path and a photo detector mounted on the surface of the printed circuit board laminate in light communication with the light via, using the bond pads formed adjacent the light via.

15. High speed data interconnect apparatus as claimed in claim 1 further including a printed circuit board affixed to an edge of the stiffening plate and printed circuit board laminate adjacent another one of the opposed ends of the

optical fiber, the another one of the opposed ends of the optical fiber being optically accessible at the printed circuit board.

16. High speed data interconnect apparatus as claimed in claim 1 wherein the stiffening plate has a higher Modulus of Elasticity than the laminate to constrain movement of a top surface of laminate relative to the stiffening plate.

17. High speed data interconnect apparatus as claimed in claim 16 wherein the printed circuit board laminate has a thickness in a range of up to two times a thickness of the stiffening plate.

18. High speed data interconnect apparatus comprising:

a stiffening plate with an elongated optical fiber mounting groove defined on a surface thereof;

a length of optical fiber with first and second opposed ends and defining an optical path between the opposed ends, the optical fiber being mounted in the groove on the surface of the stiffening plate in a longitudinally extending direction generally parallel to the surface of the stiffening plate;

a first reflecting surface positioned adjacent the first opposed end of the optical fiber, the first reflecting surface being positioned to direct light at an angle of approximately ninety degrees to the optical path and a second reflecting surface positioned adjacent the second opposed end of the optical fiber, the second reflecting surface being positioned to direct light at an angle of approximately ninety degrees to the optical path;

a printed circuit board laminate encasing the stiffening plate and the optical fiber and including a first light via for the passage of light reflected by the first reflecting surface and a second light via for the passage of

light reflected by the second reflecting surface, and first bond pads formed on a surface of the printed circuit board laminate adjacent the first light via and second bond pads formed on a surface of the printed circuit board laminate adjacent the second light via;

a vertical cavity surface emitting laser mounted on the surface of the printed circuit board laminate in light communication with the first light via, using the first bond pads formed adjacent the first light via; and

a photo detector mounted on the surface of the printed circuit board laminate in light communication with the second light via, using the second bond pads formed adjacent the second light via.

19. High speed data interconnect apparatus as claimed in claim 18 wherein the stiffening plate has a higher Modulus of Elasticity than the laminate to constrain movement of a top surface of laminate relative to the stiffening plate.

20. High speed data interconnect apparatus as claimed in claim 19 wherein the printed circuit board laminate has a thickness in a range of up to two times a thickness of the stiffening plate.

21. High speed data interconnect apparatus as claimed in claim 18 wherein the elongated optical fiber mounting groove includes one of a generally rectangular shaped cross-section with a depth and width approximately equal to a diameter of the length of optical fiber, a shallow rectangular shaped cross-section with a depth and width smaller than a diameter of the length of optical fiber, and a generally V-shaped cross-section.

22. High speed data interconnect apparatus as claimed in claim 18 wherein the first and second reflecting surfaces each include one of a cut in the optical fiber adjacent one of the first and second opposed ends of the optical fiber, respectively, defining a cut surface positioned at an angle of approximately 45 degrees to the optical path and in optical alignment with the optical path and the one of the first and second light vias, respectively, a micro mirror mounted in the groove on the surface of the stiffening plate

in optical alignment with the optical path and one of the first and second light vias, respectively, and an optical fiber portion with an approximately 45 degree mirrored end mounted in the groove on the surface of the stiffening plate in optical alignment with the optical path and one of the first and second light vias, respectively.

23. High speed data interconnect apparatus
comprising:

a stiffening plate with an elongated optical fiber
mounting groove defined on a surface thereof;

a length of optical fiber with first and second opposed
ends and defining an optical path between the opposed ends,
the optical fiber being mounted in the groove on the surface
of the stiffening plate in a longitudinally extending
direction generally parallel to the surface of the
stiffening plate;

a printed circuit board laminate encasing the
stiffening plate and the optical fiber and including a first
via through the laminate and a second via through the
laminate, and at least first bond pads formed on a surface
of the printed circuit board laminate adjacent the first
light via; and

an optical element electrically coupled to the first
bond pads and positioned adjacent the first via in optical
alignment with the first end of the length of optical fiber.

24. High speed data interconnect apparatus as claimed in claim 23 wherein the stiffening plate has a higher Modulus of Elasticity than the laminate to constrain movement of a top surface of laminate relative to the stiffening plate.

25. High speed data interconnect apparatus as claimed in claim 24 wherein the printed circuit board laminate has a thickness in a range of up to two times a thickness of the stiffening plate.

26. A method of fabricating high speed data interconnect apparatus comprising the steps of:

providing a stiffening plate with an optical fiber mounting groove defined on a surface thereof;

providing a length of optical fiber with opposed ends defining an optical path between the opposed ends and mounting the optical fiber in the groove on the surface of the stiffening plate in a longitudinally extending direction generally parallel to the surface of the stiffening plate;

positioning a reflecting surface adjacent one of the opposed ends of the optical fiber, the reflecting surface being positioned to direct light at an angle of approximately ninety degrees to the optical path between the opposed ends of the optical fiber; and

using a printed circuit board laminate, encasing the stiffening plate and the optical fiber and forming a light via through the laminate for the passage of light reflected by the reflecting surface, forming bond pads on a surface of the printed circuit board laminate adjacent the light via for the electrical connection of a light element.

27. A method as claimed in claim 26 including a step of electrically mounting on the bond pads one of a vertical cavity surface emitting laser and a photo diode in light communication with the light via.

28. A method as claimed in claim 26 wherein the step of positioning a reflecting surface includes forming the reflecting surface by one of cutting the optical fiber adjacent one of the first and second opposed ends of the optical fiber to define a cut surface positioned at an angle of approximately 45 degrees to the optical path and in optical alignment with the optical path and the one of the first and second light vias, providing a micro mirror and mounting the micro mirror in the groove on the surface of the stiffening plate in optical alignment with the optical path and one of the first and second light vias, and forming an optical fiber portion with an approximately 45 degree mirrored end and mounting the optical fiber portion in the groove on the surface of the stiffening plate in optical alignment with the optical path and one of the first and second light vias.